

PRELIMINARY SPEC

Part Number: AA3021VWC1S

White



ATTENTION
OBSERVE PRECAUTIONS
FOR HANDLING
ELECTROSTATIC
DISCHARGE
SENSITIVE
DEVICES

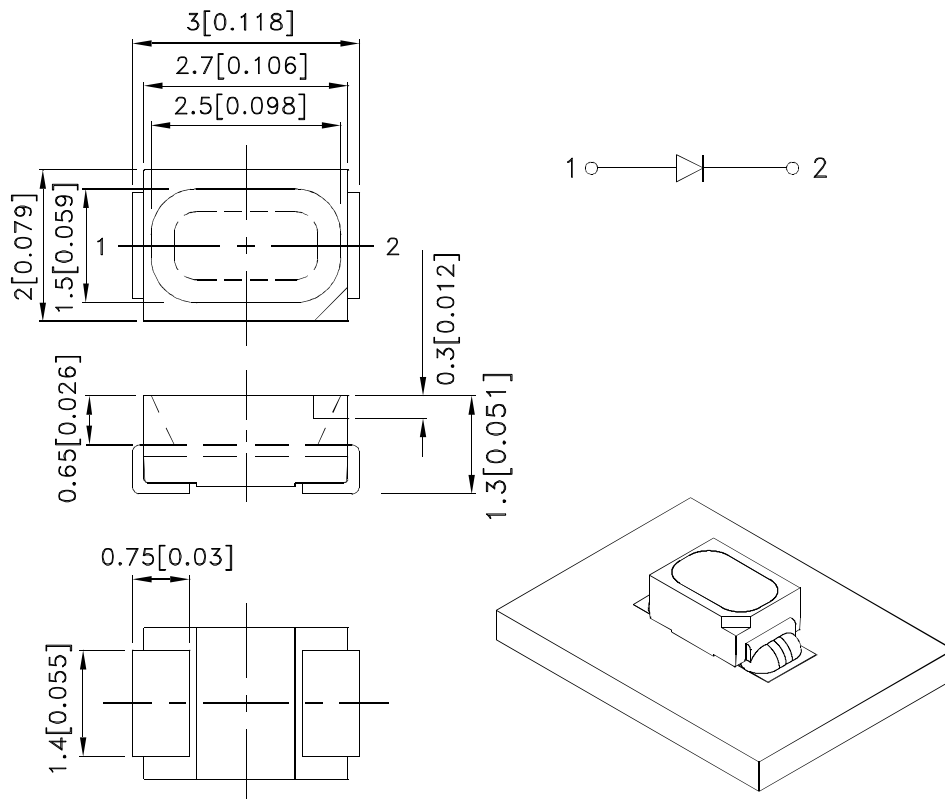
Features

- 3.0mm x 2.0mm, 1.3mm high, only minimum space required.
- Suitable for compact optoelectronic applications.
- Low power consumption.
- Package : 2000pcs / reel.
- Moisture sensitivity level : level 4.
- RoHS compliant.

Description

The source color devices are made with InGaN Light Emitting Diode.
Static electricity and surge damage the LEDs.
It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs.
All devices, equipment and machinery must be electrically grounded.

Package Dimensions



Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.2(0.008)$ unless otherwise noted.
3. Specifications are subject to change without notice.
4. The device has a single mounting surface. The device must be mounted according to the specifications.

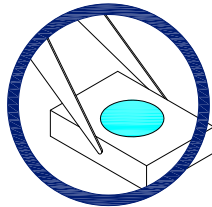


Handling Precautions

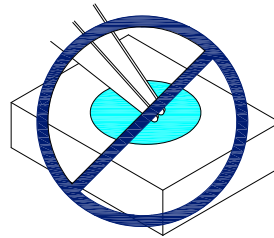
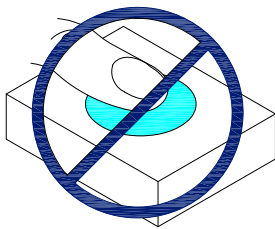
Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force.

As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might leads to damage and premature failure of the LED.

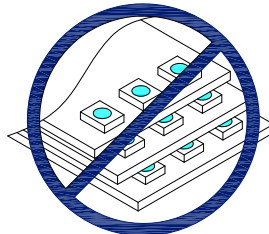
1. Handle the component along the side surfaces by using forceps or appropriate tools.



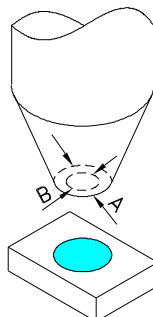
2. Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry.



3. Do not stack together assembled PCBs containing exposed LEDs. Impact may scratch the silicone lens or damage the internal circuitry.



4. The outer diameter of the SMD pickup nozzle should not exceed the size of the LED to prevent air leaks. The inner diameter of the nozzle should be as large as possible.
5. A pliable material is suggested for the nozzle tip to avoid scratching or damaging the LED surface during pickup.
6. The dimensions of the component must be accurately programmed in the pick-and-place machine to insure precise pickup and avoid damage during production.



Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) [2] @ 20mA		Viewing Angle [1]
			Min.	Typ.	2θ1/2
AA3021VWC1S	White (InGaN)	WATER CLEAR	900	1700	125°

Notes:

1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
2. Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
V _F [1]	Forward Voltage	White	3.3	4.0	V	I _F =20mA
I _R	Reverse Current	White		10	uA	V _R = 5V
X [2]	Chromaticity Coordinates	White	0.31			
Y [2]			0.31			
C	Capacitance	White	100		pF	V _F =0V;f=1MHz

Notes:

1. Forward Voltage: +/-0.1V.
2. Measurement tolerance of the chromaticity coordinates is ±0.01 .

Absolute Maximum Ratings at TA=25°C

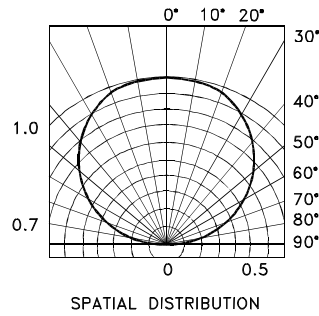
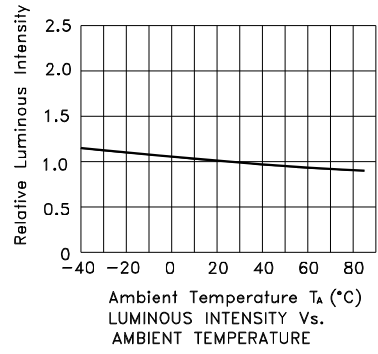
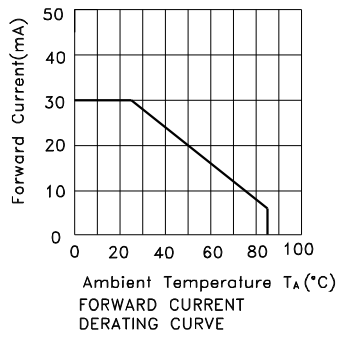
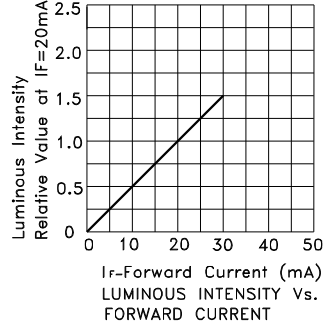
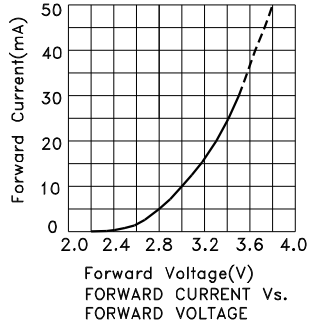
Parameter	White	Units
Power dissipation	120	mW
DC Forward Current	30	mA
Peak Forward Current [1]	100	mA
Reverse Voltage	5	V
Operating Temperature	-40°C To +85°C	
Storage Temperature	-40°C To +85°C	

Note:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.

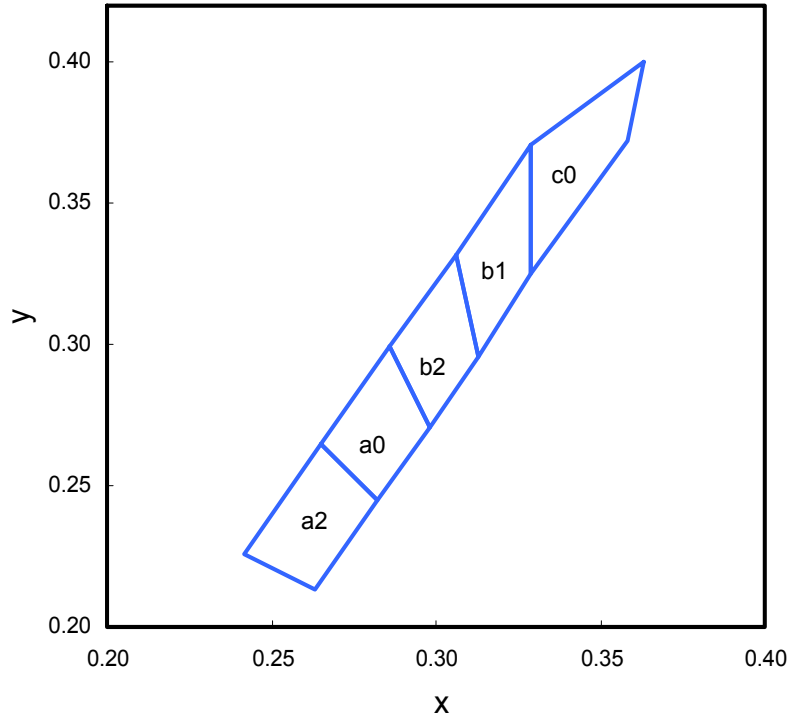
White

AA3021VWC1S



AA3021VWC1S

White CIE

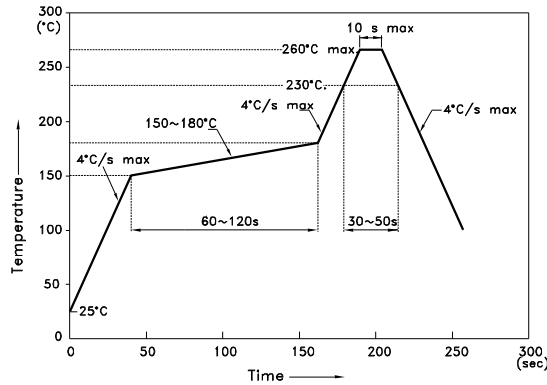


	x	y		x	y		x	y
a2	0.263	0.213	a0	0.282	0.245	b2	0.298	0.271
	0.282	0.245		0.298	0.271		0.313	0.296
	0.265	0.265		0.286	0.299		0.306	0.332
	0.242	0.226		0.265	0.265		0.286	0.299
b1	0.313	0.296	c0	0.329	0.325			
	0.329	0.325		0.358	0.372			
	0.329	0.371		0.363	0.400			
	0.306	0.332		0.329	0.371			

AA3021VWC1S

Reflow soldering is recommended and the soldering profile is shown below.
Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.

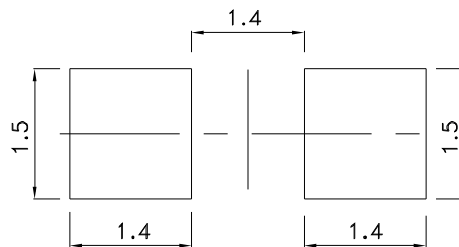


NOTES:

1. We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.
2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
3. Number of reflow process shall be 2 times or less.

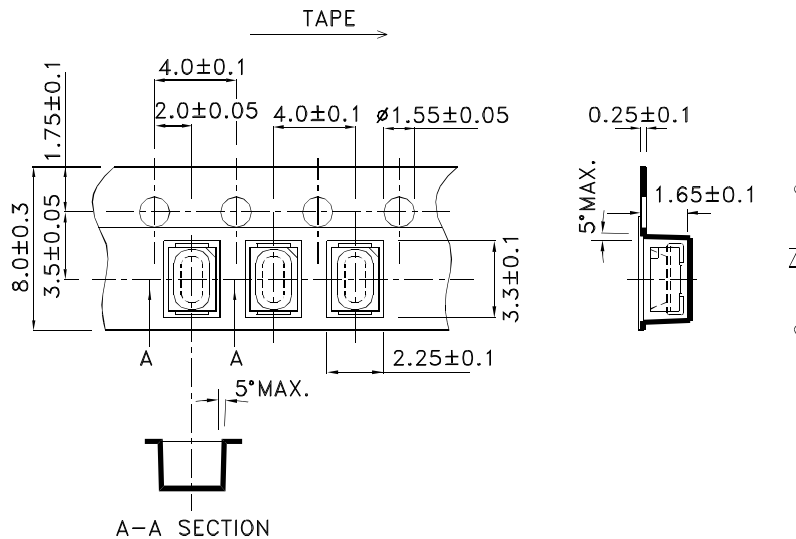
Recommended Soldering Pattern

(Units : mm; Tolerance: ± 0.1)



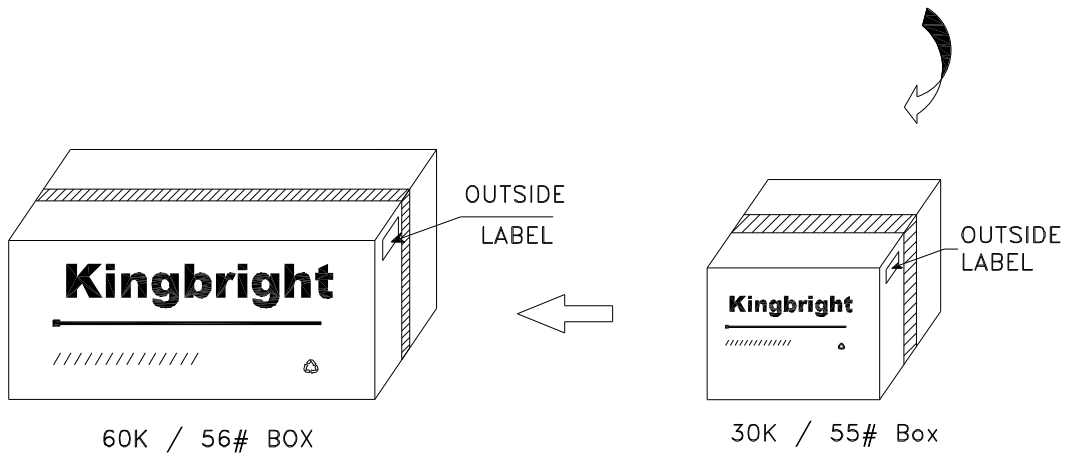
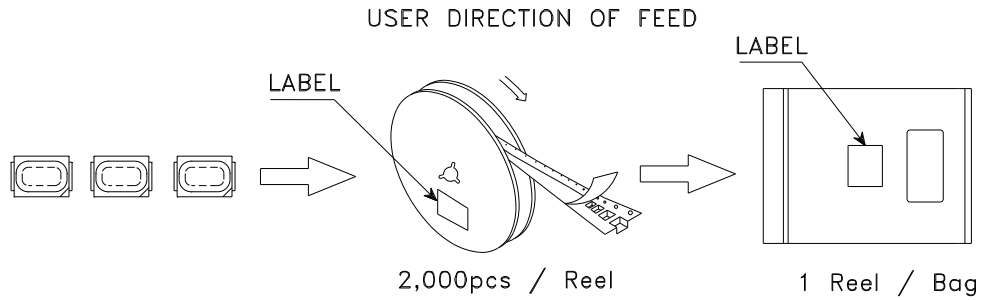
Tape Dimensions


(Units : mm)



PACKING & LABEL SPECIFICATIONS

AA3021VWC1S



<h1>Kingbright</h1>	
P/NO: AA3021xxx	
QTY: 2,000 pcs	Q.C. Q C xx xx xxxx PASSED
S/N: XXXX	
CODE: XXX	
LOT NO:	
 xxxxxxxxxxxxxxxxxxxxxxxxxxxx	
RoHS Compliant	